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U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

To the Honorable Commissioner of Patents

100752751

Attached original documents or copy thereof

1. Name of conveying party(ies):

Yuichi NAKAYOSHI

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies):

Name: Komatsu Electronic Metals Co., Ltd.

Internal Address: \_\_\_\_\_

Street Address: 2612, Shinomiya, Hiratsuka-shi Kanagawa, Japan

City: State: ZIP:

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other \_\_\_\_\_

Execution Date: June 9, 1998

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: June 17, 1998

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Gerald T. Shekleton, Esq.

Internal Address: \_\_\_\_\_

Street Address: WELSH & KATZ, LTD. 120 South Riverside Plaza / 22nd Floor

City: Chicago State: Illinois ZIP: 60603-3913

6. Total number of applications and patents involved:

7. Total Fee (37 CFR 3.41) ..... \$40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gerald T. Shekleton  
Name of Person Signing

Gerald T. Shekleton  
Signature

June 17, 1998  
Date

Total number of pages including cover sheet, attachments, and document:

Mail documents to be recorded with required cover sheet information to:

Assistant Commissioner for Patents  
Box Assignments  
Washington, D.C. 20231

PATENT  
REEL: 9269 FRAME: 0405

06/29/1998 JMWTKINS 0000001 0988712 990.00 UP

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# ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:  
AN APPARATUS FOR POLISHING A SEMICONDUCTOR WAFER

(Title of Invention)

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for  
United States Letters Patent on \_\_\_\_\_, 19\_\_\_\_ (Serial No. \_\_\_\_\_); and

WHEREAS, Komatsu Electronic Metals Co., Ltd.

(Full Name of Assignee)

a corporation of Japan

(Country of Incorporation)

whose post office address is 2612, Shinomiya, Hiratsuka-shi, Kanagawa, Japan

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/We, as assignor(s), have sold, assigned, transferred and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

|   |                         |              |
|---|-------------------------|--------------|
| 1. FULL NAME OF SOLE OR FIRST ASSIGNOR  | ASSIGNOR'S SIGNATURE    | DATE         |
| Yuichi Nakayoshi  | <i>Yuichi Nakayoshi</i> | June 9, 1998 |
| ADDRESS   | CITIZENSHIP             |              |
| c/o Komatsu Electronic Metals Co., Ltd.,<br>2612, Shinomiya, Hiratsuka-shi, Kanagawa, Japan | Japanese                |              |
| 2. FULL NAME OF SECOND ASSIGNOR, IF ANY   | ASSIGNOR'S SIGNATURE    | DATE         |
| ADDRESS   | CITIZENSHIP             |              |
| 3. FULL NAME OF THIRD ASSIGNOR, IF ANY  | ASSIGNOR'S SIGNATURE    | DATE         |
| ADDRESS   | CITIZENSHIP             |              |
| 4. FULL NAME OF FOURTH ASSIGNOR, IF ANY   | ASSIGNOR'S SIGNATURE    | DATE         |
| ADDRESS   | CITIZENSHIP             |              |
| 5. FULL NAME OF FIFTH ASSIGNOR, IF ANY  | ASSIGNOR'S SIGNATURE    | DATE         |
| ADDRESS   | CITIZENSHIP             |              |
| 6. FULL NAME OF SIXTH ASSIGNOR, IF ANY  | ASSIGNOR'S SIGNATURE    | DATE         |
| ADDRESS   | CITIZENSHIP             |              |

PATENT